

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1-9. (Canceled)

10. (Currently Amended) ~~The A~~ photosensitive resin composition ~~as set forth in claim 2, wherein the (meth)acryls, comprising a base resin component (A) and a (meth)acrylic compound (B) as essential components, wherein~~

the base resin component (A) is a polyimide resin (A-1) having at least either a hydroxyl group or a carboxyl group in its structure or a polyamide resin (A-2) having at least either a hydroxyl group, and

the (meth)acrylic compound (B) is an epoxy (meth)acrylate having at least two hydroxyl groups in its molecule.

11- 20 (Canceled).

21. (Currently amended) ~~The A~~ photosensitive resin composition ~~as set forth in claim 12, wherein the (meth)acryls, comprising a base resin component (A) and a (meth)acrylic compound (B) as essential components, wherein~~

the base resin component (A) is a polyimide resin (A-1) having at least either a hydroxyl group or a carboxyl group in its structure and the polyimide resin (A-1) is a photosensitive polyimide resin (A-1-2) obtained by reacting a compound having a carbon-carbon double bond with a polyimide resin having a hydroxyl group in its structure, and

the (meth)acrylic compound (B) is an epoxy (meth)acrylate having at least two hydroxyl groups in its molecule-, and

the photosensitive resin composition further includes, as an accessory component (C), at least one kind (C-1) selected from a photoreaction initiator, a sensitizer, and a photopolymerization assistant.

22 – 49. (Cancelled).